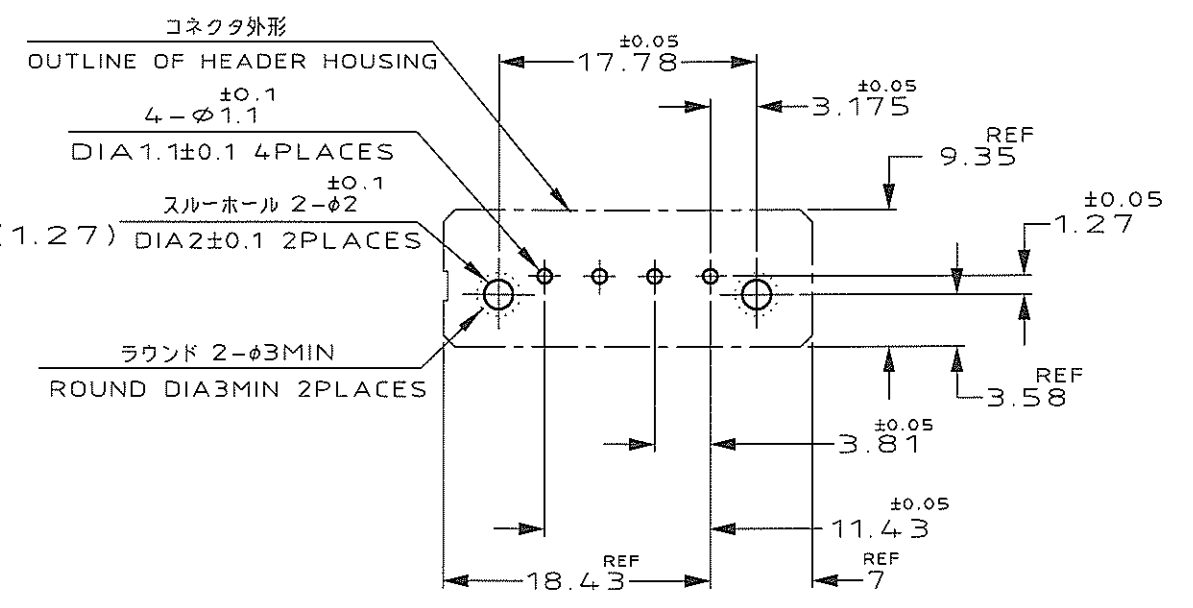
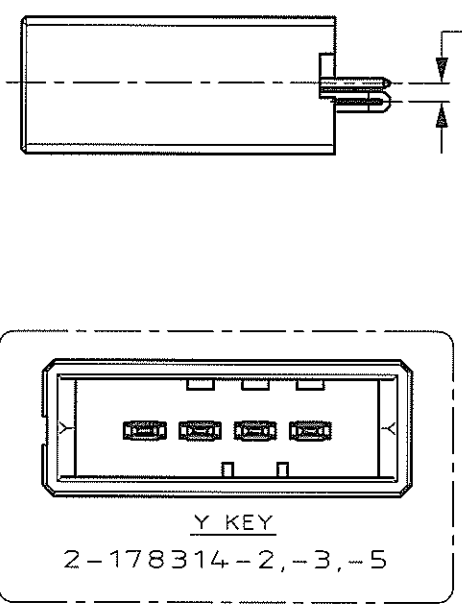
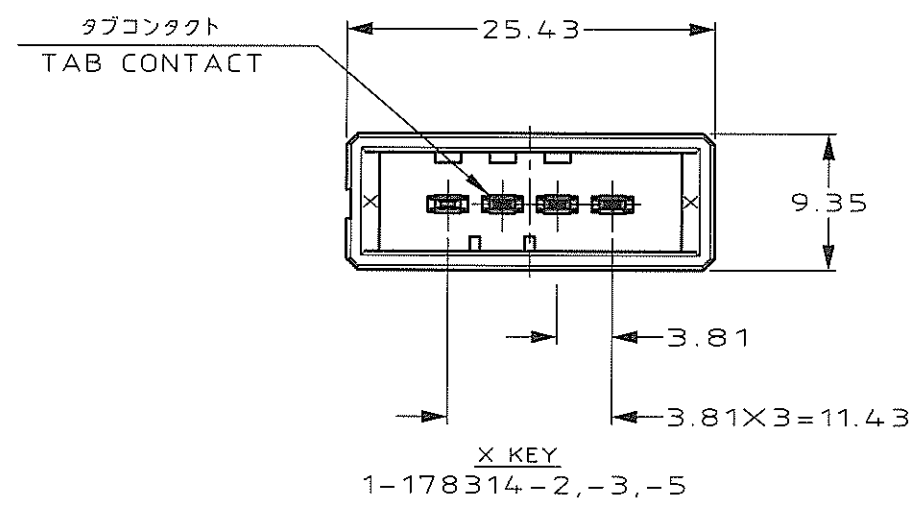
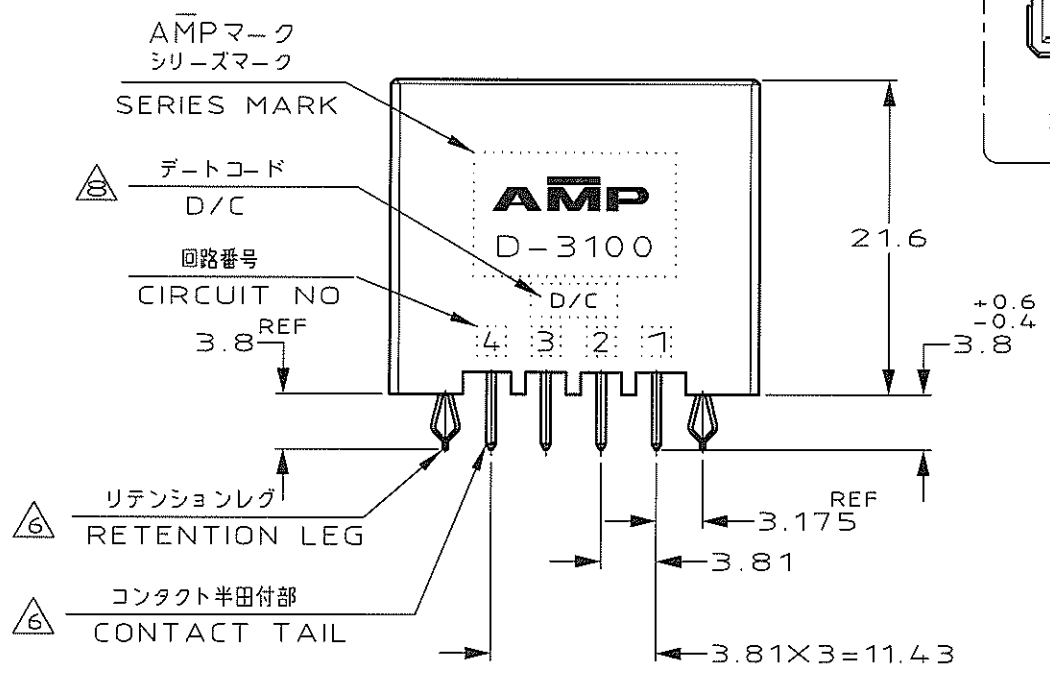


NUMBER 178314
 METRIC
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST



推奨基板取付け寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38μm PdNi & Au PLATING OVER NICKEL
- FINISH (CONTACT AREA): 0.76μm PdNi & Au PLATING OVER NICKEL
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
- THE SHAPE, SIZE AND POSITION OF THE CHARACTER SHOW THE OUTLINE THEY DON'T SHOW DETAILS
- THE DATE CODE SHOW PRODUCTION LOT BY NUMBER. THE NUMBER MAKE UP THE NUMBER OF FOUR COLUMNS OR FIVE COLUMNS. (INCLUDE THE ALPHABET)

△6	△4	1,2-178314-5
△6	△3	1,2-178314-3
△6	△2	1,2-178314-2
(FINISH)		製品番号 (PART NO.)

E	REVISED PER ECR-25-250788	F.Z	R.B	16 JAN 2025
D2	REVISED	Y.O	T.K	19 OCT 2009
D1	REVISED (ECR-08-027321)	T.S	A.O	29 OCT 2008
D	REVISED (ECR-07-020412)	Y.Y	D.M	28 AUG 2007
C	REVISED (FJD0-0039-03)	T.S	S.M	2 JUN '03
B	REVISED (FJD0-0114-03)	T.S	SM	25 APR '03
A	REVISED (FJ00-2183-95)	KI	SM	3-23 '95
O	RELEASED (FJ00-1468-94)	KI	S.M	10/JAN/95
LTR	REVISION RECORD	DR	CHK	DATE CHK.

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STE TE Connectivity

WIRE RANGE	INSULATION DIA	NAME
mm ² (AWG)	mmφ	ダイナミック 3100 シリーズ 4極 ヘッダーアセンブリー (垂直タイプ) 4 POS SINGLE ROW VERTICAL HDR ASS'Y FOR DYNAMIC 3100
MATERIAL	FINISH	一般公差 (GENERAL TOLERANCE)
SEE NOTE 注記参照	SEE NOTE 注記参照	10mmF : ±0.3 10mmB 30mmF : ±0.4 30mmB 100mmF : ±0.45 角 度 : ±3'
DR. K.IKEDA 22/DEC/94	DE. K.IKEDA 22/DEC/94	SIZE LOC NUMBER
10/JAN/95	10/JAN/95	A3 J C-178314
S.MANABE	S.MANABE	SCALE REV. SHEET
		2-1 E 1 OF 1